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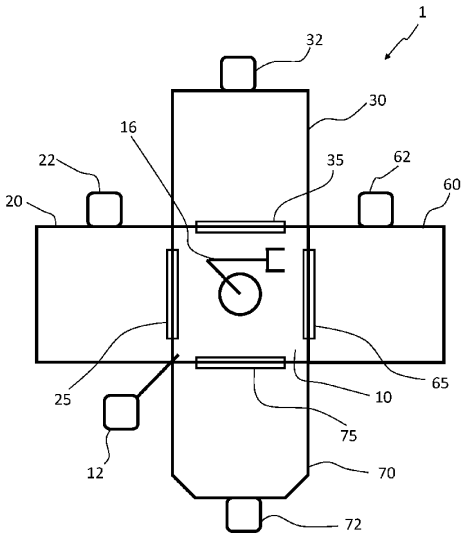


Fig. 1

(57) Abstract: The invention relates to a method and apparatus for processing surface of a substrate (100) with a cluster apparatus (1) comprising a transport chamber (10) and two or more process reactors (20, 30, 40, 60) connected to the transport chamber (10). The method further comprises subjecting the surface of the substrate (100) to a surface preparation step for providing a prepared substrate surface, providing an interface layer on the prepared substrate surface of the substrate (100) for forming an interfaced substrate surface, and providing a functional layer on the interfaced substrate surface of the substrate (100). The process steps are carried out in at least two different process reactors (20, 30, 40, 60) connected to transport chamber (10) the substrate (100) is transported between the at least two process reactors (20, 30, 40, 60) via the transport chamber (10) under vacuum atmosphere.

WO 2021/058872 A1

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